



Title of Change:	Package assembly site transfer for narrow body SOIC packages from Amkor and/ or ASE Chung Li to ASE Kunshan
Proposed First Ship date:	23 Oct 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Lay Woon Lim < LayWoon.Lim@onsemi.com >
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >
Marking of Parts/ Traceability of Change:	Parts can be identified by the assembly code in the traceability code
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
None	ASECL, Taiwan (ChungLi)
	ASEKS, China
	ATP1 - Amkor Technology Philippines P1

Description and Purpose:

This Initial PCN is to notify of the pending action to qualify a new package assembly site, ASE located in Kunshan, China (ASEKS) for narrow body SOIC-8 and SOIC-16 packages that are currently assembled in Amkor Tech Philippines Plant 1 and/ or ASE in Chung Li. This change is to allow ON Semiconductor to consolidate the package assembly manufacturing of SOIC packages to limited sites for better supply chain management and manufacturing flexibility. The package BOM will be changed to the standard BOM for the SOIC packages at ASEKS. Due to specific tooling requirement at ASEKS, a few minor physical dimension parameters on the case outline drawing or physical outline drawing will be changing as detailed below.

	Before Change Description	After Change Description
Assembly Site	Amkor Tech Philippines Plant 1 ASE Chung Li	ASE Kunshan
Die Attach	Henkel EPOXY 8290, EPOXY 84-1 LMIS R4 Hitachi EN4900G	Hitachi EN4900GC
Mold Compound	Sumitomo EME-6600H, EME-G600, G700LS Sumitomo G700LY	Hitachi CEL-9240HF10AK

	From	To
Product marking change	Assembly Site Code for Amkor or ASE Chung Li	Latest marking style format. Assembly Site Code for ASEKS.



	From	To															
<p>Case Outline Drawing Changes</p> <p>SOIC-8 Case Outline # 751AZ Document # 98AON34918E SOIC-16 Case Outline # 751BA Document # 98AON34919E</p>	<table border="1"> <thead> <tr> <th colspan="3">case outline 751AZ (mm)</th> </tr> <tr> <th>DIM</th> <th>MIN</th> <th>MAX</th> </tr> </thead> <tbody> <tr> <td>h</td> <td>0.25</td> <td>0.41</td> </tr> </tbody> </table>	case outline 751AZ (mm)			DIM	MIN	MAX	h	0.25	0.41	<table border="1"> <thead> <tr> <th>DIM</th> <th>MIN</th> <th>MAX</th> </tr> </thead> <tbody> <tr> <td>h</td> <td>0.25</td> <td>0.50</td> </tr> </tbody> </table>	DIM	MIN	MAX	h	0.25	0.50
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Qualification Plan:

QV DEVICE NAME: QV1, QV2, QV3, QV4

RMS: TBD

PACKAGE: SOIC-8, SOIC-16

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC+PC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
UHASt+PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 2 @ 260 °C	
SD	JSTD002	Ta = 245C, 5 sec	

Estimated date for qualification completion: 2 July 2021

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FS7140-01G-XTP	FS7140-01G-XTD
FS7140-01G-XTD	FS7140-01G-XTD
FS6377-01IG-XTD	FS6370-01G-XTD
FS6377-01G-XTP	FS6370-01G-XTD
FS6377-01G-XTD	FS6370-01G-XTD